nventor:

Kie Y. Ahn et al.

A Dielectric Layer Forming Method and Devices Formed Therewith

Assignee:

Micron Technology, Inc.

Docket No. MI22-1534

INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The attached form PTO-1449 is submitted in compliance with 37 CFR §1.56. Copies of documents listed on the Form PTO-1449 are enclosed.

No admission is made regarding whether all the submitted references are prior art.

Respectfully submitted,

Dated: 16 Sep 2003

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

ATTY. DOCKET NO. MI22-1534 SERIAL NO. 09/881,408

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LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)

APPLICANT Kie Y. Ahn, et al

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FILING DATE June 13, 2001 U.S. PATENT DOCUMENTS *Examiner Document Date Name Class Subclass Filing Date													
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